

NTUD3129PT5G Datasheet

 onsemi

DiGi Electronics Part Number	NTUD3129PT5G-DG
Manufacturer	onsemi
Manufacturer Product Number	NTUD3129PT5G
Description	MOSFET 2P-CH 20V 0.14A SOT963
Detailed Description	Mosfet Array 20V 140mA 125mW Surface Mount SO T-963

<https://www.DiGi-Electronics.com>



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

NTUD3129PT5G

Series:

-

Technology:

MOSFET (Metal Oxide)

FET Feature:

Logic Level Gate

Current - Continuous Drain (Id) @ 25°C:

140mA

Vgs(th) (Max) @ Id:

1V @ 250µA

Input Capacitance (Ciss) (Max) @ Vds:

12pF @ 15V

Operating Temperature:

-55°C ~ 150°C (TJ)

Package / Case:

SOT-963

Base Product Number:

NTUD31

Manufacturer:

onsemi

Product Status:

Obsolete

Configuration:

2 P-Channel (Dual)

Drain to Source Voltage (Vdss):

20V

Rds On (Max) @ Id, Vgs:

50hm @ 100mA, 4.5V

Gate Charge (Qg) (Max) @ Vgs:

-

Power - Max:

125mW

Mounting Type:

Surface Mount

Supplier Device Package:

SOT-963

Environmental & Export classification

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

REACH Status:

REACH Unaffected

HTSUS:

8541.21.0095

NTUD3129P

Small Signal MOSFET

-20 V, -180 mA, Dual P-Channel,
1.0 x 1.0 mm SOT-963 Package



ON Semiconductor®

<http://onsemi.com>

Features

- Dual P-Channel MOSFET
- Offers a Low $R_{DS(ON)}$ Solution in the Ultra Small 1.0 x 1.0 mm Package
- 1.5V Gate Voltage Rating
- Ultra Thin Profile (< 0.5 mm) Allows It to Fit Easily into Extremely Thin Environments such as Portable Electronics.
- These are Pb-Free Devices

Applications

- General Purpose Interfacing Switch
- Optimized for Power Management in Ultra Portable Equipment

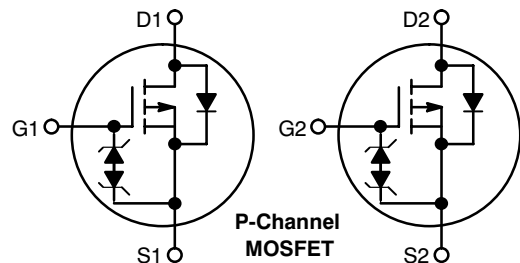
MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		V_{DSS}	-20	V	
Gate-to-Source Voltage		V_{GS}	± 8	V	
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	I_D	-140	
				$T_A = 85^\circ\text{C}$	-100
	$t \leq 5$ s	$T_A = 25^\circ\text{C}$		-180	mA
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	P_D	-125	
				$t \leq 5$ s	-200
Pulsed Drain Current		$t_p = 10$ μs	I_{DM}	-600	mA
Operating Junction and Storage Temperature		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$	
Source Current (Body Diode) (Note 2)		I_S	-200	mA	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		T_L	260	$^\circ\text{C}$	

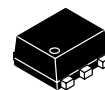
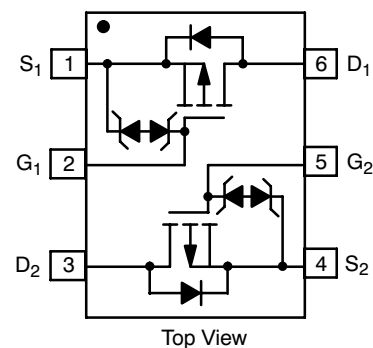
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface-mounted on FR4 board using the minimum recommended pad size, 1 oz Cu.
2. Pulse Test: pulse width ≤ 300 μs , duty cycle $\leq 2\%$

$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	I_D Max
-20 V	5.0 Ω @ -4.5 V	-0.18 A
	7.0 Ω @ -2.5 V	
	10 Ω @ -1.8 V	
	14 Ω @ -1.5 V	

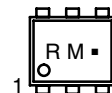


PINOUT: SOT-963



SOT-963
CASE 527AA

MARKING DIAGRAM



R = Specific Device Code
M = Date Code
▪ = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

NTUD3129P

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	1000	°C/W
Junction-to-Ambient – $t = 5$ s (Note 3)		600	

3. Surface-mounted on FR4 board using the minimum recommended pad size, 1 oz Cu.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}, V_{DS} = -5.0\text{ V}$	$T_J = 25^\circ\text{C}$		-50	nA
			$T_J = 85^\circ\text{C}$		-200	
		$V_{GS} = 0\text{ V}, V_{DS} = -16\text{ V}$	$T_J = 25^\circ\text{C}$		-100	
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5.0\text{ V}$			± 100	nA

ON CHARACTERISTICS (Note 4)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\ \mu\text{A}$	-0.4		-1.0	V
Drain-to-Source On Resistance	$R_{DS(ON)}$	$V_{GS} = -4.5\text{ V}, I_D = -100\text{ mA}$		4.0	5.0	Ω
		$V_{GS} = -2.5\text{ V}, I_D = -50\text{ mA}$		5.0	7.0	
		$V_{GS} = -1.8\text{ V}, I_D = -20\text{ mA}$		6.5	10	
		$V_{GS} = -1.5\text{ V}, I_D = -10\text{ mA}$		7.5	14	
		$V_{GS} = -1.2\text{ V}, I_D = -1.0\text{ mA}$		11.5		
Forward Transconductance	g_{FS}	$V_{DS} = -5.0\text{ V}, I_D = -125\text{ mA}$		0.26		S
Source-Drain Diode Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_D = -10\text{ mA}$		-0.65	-1.0	V

CHARGES, CAPACITANCES AND GATE RESISTANCE

Input Capacitance	C_{ISS}	$f = 1\text{ MHz}, V_{GS} = 0\text{ V}$ $V_{DS} = -15\text{ V}$		12		pF
Output Capacitance	C_{OSS}			2.7		
Reverse Transfer Capacitance	C_{RSS}			1.0		

SWITCHING CHARACTERISTICS, $V_{GS} = 4.5\text{ V}$ (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -4.5\text{ V}, V_{DD} = -15\text{ V},$ $I_D = -180\text{ mA}, R_G = 2.0\ \Omega$		20		ns
Rise Time	t_r			37		
Turn-Off Delay Time	$t_{d(OFF)}$			112		
Fall Time	t_f			97		

4. Switching characteristics are independent of operating junction temperatures

NTUD3129P

TYPICAL PERFORMANCE CURVES

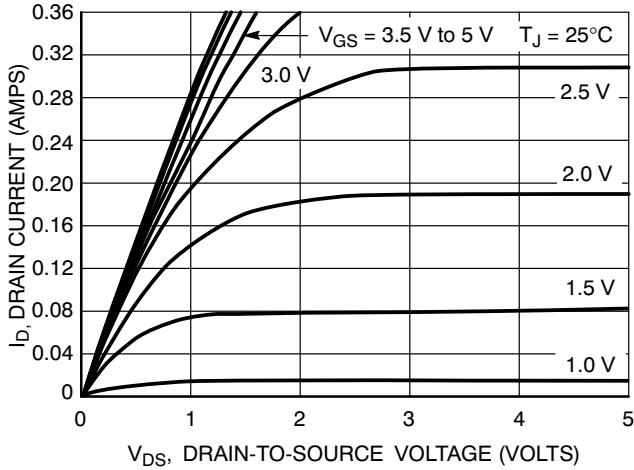


Figure 1. On-Region Characteristics

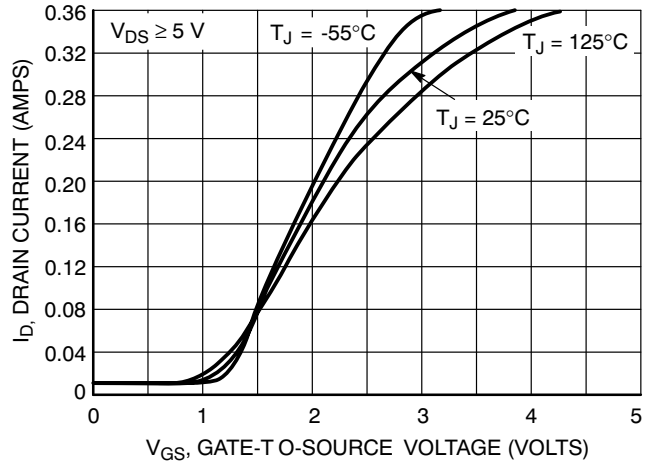


Figure 2. Transfer Characteristics

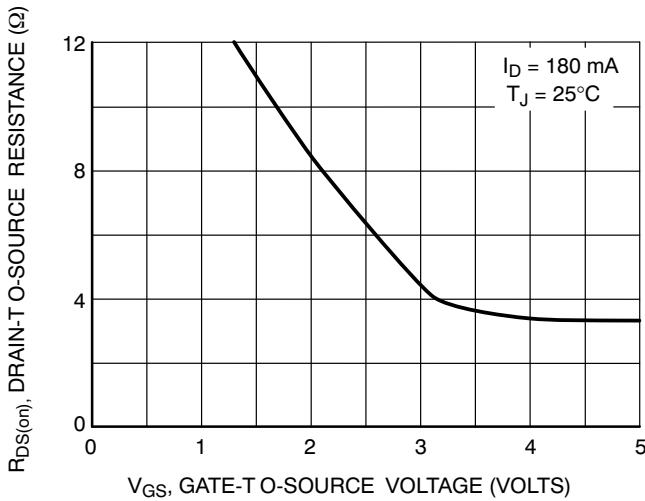


Figure 3. On-Resistance vs. Gate Voltage

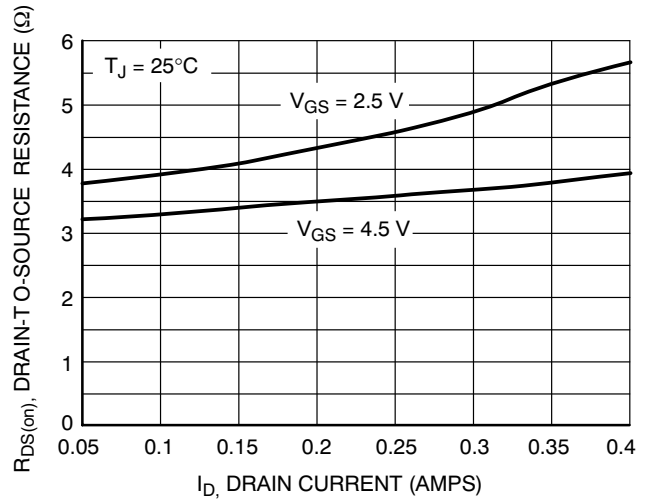


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

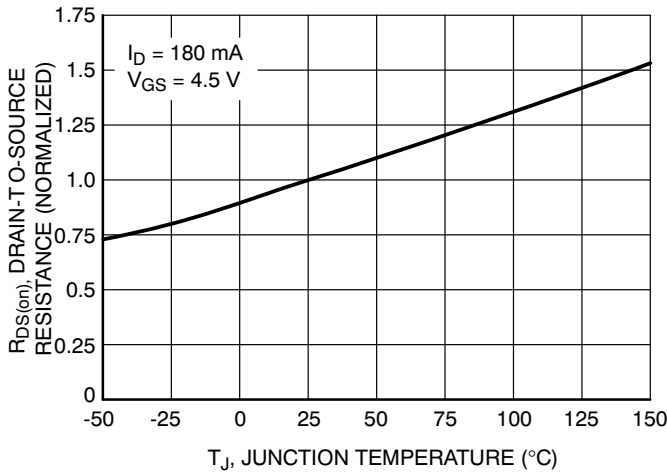


Figure 5. On-Resistance Variation with Temperature

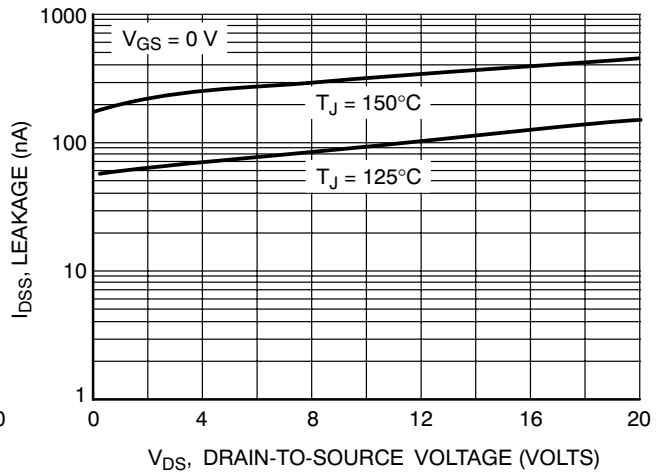


Figure 6. Drain-to-Source Leakage Current vs. Voltage

NTUD3129P

TYPICAL PERFORMANCE CURVES

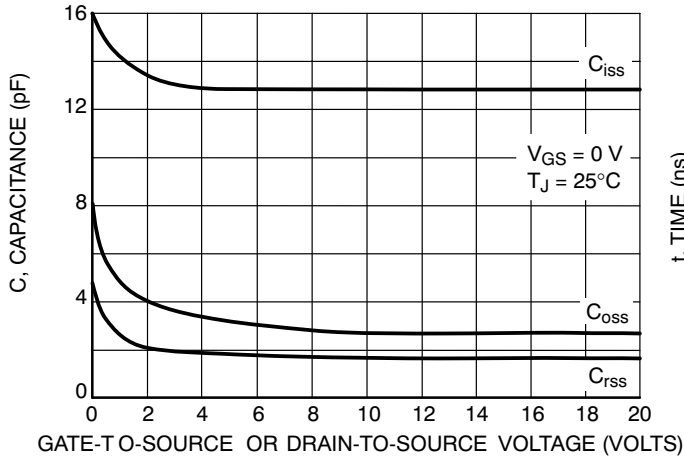


Figure 7. Capacitance Variation

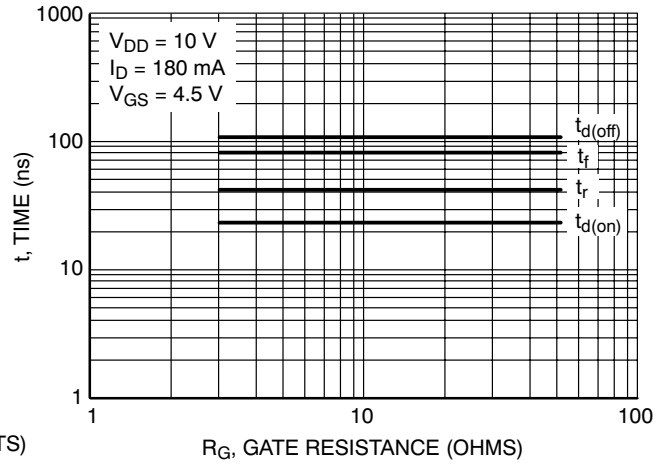


Figure 8. Resistive Switching Time Variation vs. Gate Resistance

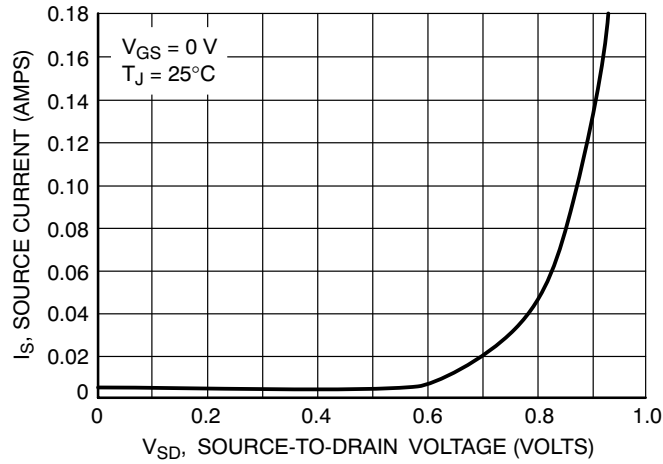


Figure 9. Diode Forward Voltage vs. Current

ORDERING INFORMATION

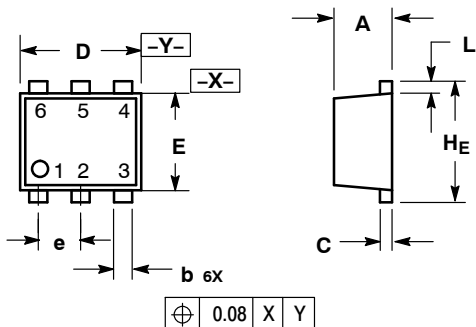
Device	Package	Shipping [†]
NTUD3129PT5G	SOT-963 (Pb-Free)	8000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SOT-963
CASE 527AA
ISSUE D

DATE 30 JUL 2008

SCALE 4:1



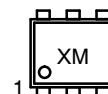
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.40	0.45	0.50	0.016	0.018	0.020
b	0.10	0.15	0.20	0.004	0.006	0.008
C	0.05	0.10	0.15	0.002	0.004	0.006
D	0.95	1.00	1.05	0.037	0.039	0.041
E	0.75	0.80	0.85	0.03	0.032	0.034
e	0.35 BSC			0.014 BSC		
L	0.05	0.10	0.15	0.002	0.004	0.006
H _E	0.95	1.00	1.05	0.037	0.039	0.041

- | | | |
|--|---|--|
| <p>STYLE 1:
PIN 1. EMITTER 1
2. BASE 1
3. COLLECTOR 2
4. EMITTER 2
5. BASE 2
6. COLLECTOR 1</p> | <p>STYLE 2:
PIN 1. EMITTER 1
2. EMITTER2
3. BASE 2
4. COLLECTOR 2
5. BASE 1
6. COLLECTOR 1</p> | <p>STYLE 3:
PIN 1. CATHODE 1
2. CATHODE 1
3. ANODE/ANODE 2
4. CATHODE 2
5. CATHODE 2
6. ANODE/ANODE 1</p> |
| <p>STYLE 4:
PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER
5. COLLECTOR
6. COLLECTOR</p> | <p>STYLE 5:
PIN 1. CATHODE
2. CATHODE
3. ANODE
4. ANODE
5. CATHODE
6. CATHODE</p> | <p>STYLE 6:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE</p> |
| <p>STYLE 7:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. ANODE
6. CATHODE</p> | <p>STYLE 8:
PIN 1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN</p> | <p>STYLE 9:
PIN 1. SOURCE 1
2. GATE 1
3. DRAIN 2
4. SOURCE 2
5. GATE 2
6. DRAIN 1</p> |
| <p>STYLE 10:
PIN 1. CATHODE 1
2. N/C
3. CATHODE 2
4. ANODE 2
5. N/C
6. ANODE 1</p> | | |

GENERIC MARKING DIAGRAM*

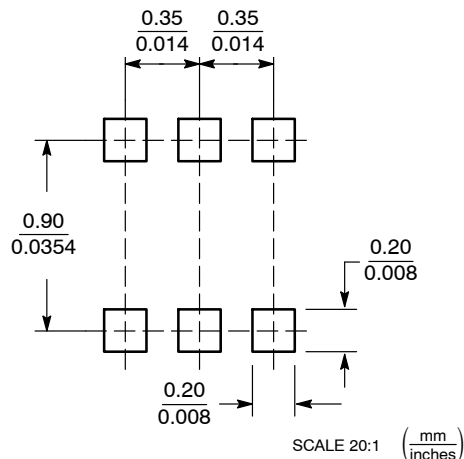


X = Specific Device Code
M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOT-963, 1X1, 0.35P	PAGE 1 OF 1

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